

**2019**

# 中国晶圆制造材料技术与市场论坛

China Wafer Fabrication Materials Tech & Market Forum

**8.28-29 杭州 Hangzhou**

主办  
Organizer



[Http://www.asiachem.org/2019FAB](http://www.asiachem.org/2019FAB)

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### 会议背景

2018年度海关数据显示，中国集成电路(IC)进口金额超过3100亿美元，比2017年增长19.8%。作为国家重点战略新兴产业，集成电路产业链的技术突破，成为业界关注的焦点。

晶圆制造是集成电路产业链的核心环节，关键材料十分重要。主要包括CMP材料、光刻胶、湿电子化学品（显影、清洗、剥离、蚀刻等）、电子气体、光掩膜版、靶材等。根据《国家集成电路产业发展推进纲要》明确要求：突破集成电路关键装备和材料，加快产业化进程，增强产业配套能力。本土企业将迎来空前发展机遇。

行业数据显示，2018年全球晶圆制造材料市场规模为近300亿美元。随着中国Fab厂陆续建成投产，未来关键材料和化学品市场将有广大的增长空间。由于技术壁垒和市场门槛高，目前半导体材料国产化程度较低，不到10%。欧美日韩的龙头企业占据主要市场份额。中国晶圆制造材料行业面临巨大市场机遇，技术与应用发展迫在眉睫。

首届中国晶圆制造材料技术与市场论坛2019将于8月28-29日召开。会议将重点探讨中国集成电路与晶圆制造产业政策，全球与中国晶圆产能扩张与材料需求展望，中国FAB厂投资与晶圆制造材料市场，海外企业最新技术，光刻胶、湿电子化学品、高纯电子气体、溅射靶材、光掩膜版、CMP材料的技术与市场趋势，以及国产化率提升的机遇与挑战等。

### 会议主题

- 1.中国集成电路与晶圆制造产业政策
- 2.全球与中国晶圆产能扩张与材料需求展望
- 3.中国Fab厂投资布局与晶圆制造材料市场
- 4.海内外领先的材料与技术进展
- 5.光刻胶技术与市场现状与前沿动向：KrF/ArF/EUV
- 6.半导体湿电子化学品的国产化提升
- 7.高纯电子气体供需与投资机遇
- 8.高纯溅射靶材与光掩膜版技术与市场
- 9.CMP材料新技术与项目投资
- 10.中国半导体大硅片发展现状
- 11.工业参观与考察

### 日程安排

<b>2019年8月27日</b>	<b>周二</b>
17:00-20:00	会议报到注册
<b>2019年8月28日</b>	<b>周三</b>
08:00-09:00	会前注册
09:00-12:00	演讲报告
12:00-14:00	自助午餐与交流
14:00-18:00	演讲报告
18:00-20:00	招待晚宴
<b>2019年8月29日</b>	<b>周四</b>
09:00-16:00	工业参观

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### Background

Customs data shows, China imported more than USD 310 billion Integrated Circuit (IC), in 2018, an increase of 19.8% over 2017. As a national strategic emerging industry, the technological breakthrough of the IC industry chain has become the focus of attention.

Wafer fabrication is the core of the IC industry chain, and key materials are very important, which mainly includes CMP materials, photoresists, wet electronic chemicals (development, cleaning, stripping, etching etc.), electronic gases, photomasks, targets etc. According to the "National Integrated Circuit Industry Development Promotion Outline", it is required to break through the key equipment and materials, accelerate the process of industrialization, and enhance the supporting capacity of the industry. Local companies will face the unprecedented opportunities.

Industry data shows that the global wafer fabrication materials market is nearly \$30 billion in 2018. As China's Fab plants are completed and put into production, there will be plenty of room for growth in key materials and chemicals markets in the future. Due to technical barriers and high market thresholds, the current level of localization of semiconductor materials is relatively low, less than 10%. Leading companies in Europe, America, Japan and South Korea occupy a major market share. China's wafer fabrication materials face huge market opportunities and technology and application development are imminent.

China Wafer Fabrication Materials Tech & Market Forum 2019 will be held on Aug. 28-29. The conference will focus on China's IC and wafer fabrication industry policies, global and China wafer capacity expansion and material demand outlook, China FAB plant investment and wafer fabrication materials market, the latest technology of overseas companies, photoresist, wet electronic chemicals, high-purity electronic gas, sputtering target, photomask, CMP material technology and market trends, as well as opportunities and challenges to increase localization rate.

### Topics

1. China IC and Wafer Fabrication Industry Policies
2. Global and China wafer capacity expansion & material demand outlook
3. China Fab plants investment planning and materials market
4. Leading materials & technologies update
5. Photoresist technologies & market frontier: KrF/ArF/EUV
6. Localization of semiconductor wet electronic chemicals
7. High-purity electronic gas supply & demand and investment opportunities
8. High-purity sputtering target & photomask technologies and market
9. CMP material new technologies and projects investment
10. China's semiconductor wafer development status
11. Industrial tour

### Preliminary Agenda

#### **Aug.27, 2019 Tuesday**

17:00~20:00 Pre-conference Registration

#### **Aug.28, 2019 Wednesday**

08:00~09:00 Pre-conference Registration

09:00~12:30 Speech

12:30~14:00 Networking Lunch

14:00~18:00 Speech

18:00~20:00 Banquet

#### **Aug.29, 2019 Thursday**

09:00~16:00 Industrial visiting